



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2022-02-10
Company Unique ID	NL 008751171B01	Contact Name *	Refer to Supplier Comment section
Contact Name *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Authorized Representative *	ADG Material Declaration champion
Authorized Representative *	giovanni giacopello	Representative Title	Refer to Supplier Comment section
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS10H100SFY	VA7R*Z08PD5V	A	996I	2022-02-10
	Amount	UoM	Unit type	ST ECOPACK Grade
	90	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00568668	

Package Designator	Package Size	Nbr of instances	Shape	
Not Applicable	6.10,4.40,1.10	3	0	
Comment	PSMC-3L-EP			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption id.	Description
7a	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2002/363_March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption id.	Description
8(e)	8(e) - Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 17th Dec 2021			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.037	die	411
Lead	1.684	soft solder	18711

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GB 26572 – 2014				
Query				Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				true
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				false
Hazardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
X	O	O	O	O
Soft solder				
Homogeneous Material(s) containing Lead				

QueryList : REACH-17 Jan 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				false
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	1.68	Soft solder	18711
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				false
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article / Homogeneous Material
Lead	1000 ppm	1.68	Soft solder	924767

QueryList : Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Gold, Tin, Tungsten,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	
Query	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	
Query	Response
The product contains adhesives identified under GB 33372	false

Stockholm Convention Persistent Organic Pollutants	
Query	Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	true

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	VA7R*Z08PDSV									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	M-011 Other inorganic materials	2.464	mg	supplier	die	Silicon(Si)	7440-21-3		2.297	mg	932225	25524				
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.020	mg	8117	222				
				supplier	metallisation	Gold(Au)	7440-57-5		0.019	mg	7711	211				
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.037	mg	15016	411				
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.005	mg	2029	56				
				supplier	metallisation	Tungsten(W)	7440-33-7		0.005	mg	2029	56				
				supplier	passivation	Silicon oxide	7631-86-9		0.020	mg	8117	222				
				supplier	polymer coating	Durimide	proprietary		0.061	mg	24756	678				
				leadframe	M-004 Copper and its alloys	37.147	mg	supplier	alloy	Copper (Cu)	7440-50-8		36.051	mg	970495	400567
								supplier	alloy	Phosphorus (P)	7723-14-0		0.056	mg	1508	622
supplier	alloy	Iron (Fe)	7439-89-6						0.966	mg	26005	10733				
supplier	alloy	Zinc(Zn)	7440-66-6						0.074	mg	1992	822				
Soft solder	Solder	1.821	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	1.684	mg	924766	18711				
				supplier	solder	Tin(Sn)	7440-31-5		0.091	mg	49973	1011				
				supplier	solder	Silver(Ag)	7440-22-4		0.046	mg	25261	511				
				supplier	clip	Copper (Cu)	7440-50-8		8.659	mg	970523	96211				
Clip	M-004 Copper and its alloys	8.922	mg	supplier	clip	Phosphorus (P)	7723-14-0		0.013	mg	1457	144				
				supplier	clip	Iron (Fe)	7439-89-6		0.232	mg	26003	2578				
				supplier	clip	Zinc(Zn)	7440-66-6		0.018	mg	2017	200				
				Encapsulation	M-011 Other inorganic materials	37.998	mg	supplier	mold compound	Silica vitreous	60676-86-0		34.882	mg	917996	387578
supplier	mold compound	Phenol resin	205830-20-2						1.520	mg	40002	16889				
supplier	mold compound	Biphenyl epoxy resin	85954-11-6						0.760	mg	20001	8444				
supplier	mold compound	Oxirane, 2,2'(methylenebis(2,6-dimethyl-4,1-p	93705-66-9						0.760	mg	20001	8444				
supplier	mold compound	Carbon black	1333-86-4						0.076	mg	2000	844				
Connections coating	Solder	1.648	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.648	mg	1000000	18311				